

AMENDMENTS TO THE SPECIFICATION

Page 5, please replace the paragraph on lines 14-16 with the following amended paragraph:

~~Fig. 5 is a diagram~~ Figs. 5-7 are diagrams of a state in which the interposer is arranged at a deviated position from an arrangement position in design;

Page 5, please replace the paragraph on lines 23-25 with the following amended paragraph:

~~Fig. 10 is a diagram~~ Figs. 10-12 are diagrams of a state in which the semiconductor chip is arranged at a deviated position from the arrangement position in design;

Please replace the paragraph [0018] beginning on page 9, line 30 and ending on page 10, line 11, with the following amended paragraph:

The die bond unit 5 also creates data obtained by arranging the semiconductor chip 11 when manufacturing fluctuation (fluctuation in an arrangement position of the semiconductor chip 11 on the interposer 12) occurs in inclination in an oblique direction with respect to the arrangement position in design of the semiconductor chip 11 on the interposer 12, that is, both the X and the Y directions, for example, as shown in Fig. 11, a rotation direction (a rotation direction on an arrangement surface of the semiconductor chip on the interposer), for

example, as shown in Fig. 12, or a Z direction with respect to the main surface of the interposer (a thickness direction of the interposer). An alternate long and short dash line in Figs. 9 to 12 indicates the arrangement position in design on ~~the interposer 12~~ the semiconductor chip 11.